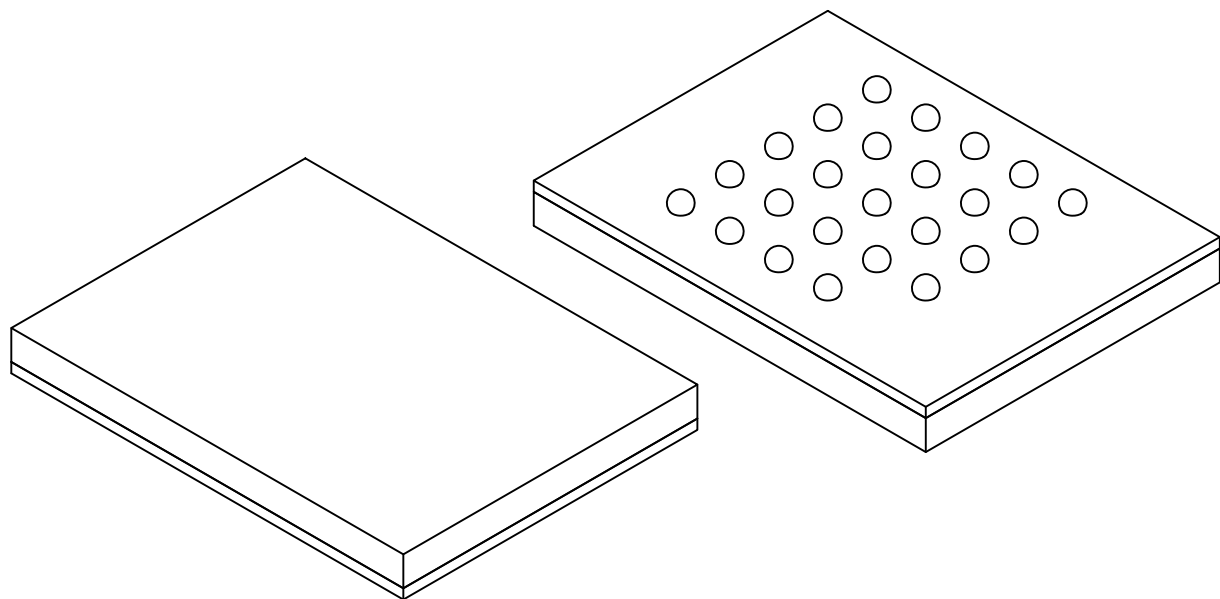


24-Ball Thin-Profile Fine-Pitch Ball Grid Array Package (8SW) - 6x8x1.2 mm Body [TFBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N	24		
Pitch	e	1.00 BSC		
Overall Height	A	1.02	1.08	1.20
Ball Height	A1	0.20	0.30	0.35
Mold Thickness	M	0.65 REF		
Substrate Thickness	S	0.30 REF		
Overall Length	D	6.00 BSC		
Ball Array Length	D2	4.00 BSC		
Overall Width	E	8.00 BSC		
Ball Array Width	E2	4.00 BSC		
Ball Diameter	b	0.35	0.40	0.45

Notes:

1. The Pin 1 visual index feature may vary, but it must be located within the hatched area.
2. The package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M
 BSC: Basic Dimension. The theoretically exact value is shown without tolerances.
 REF: Reference Dimension, usually without tolerance, is for information purposes only.